2SD2074

Silicon NPN epitaxial planar type

For low-voltage output amplification For muting

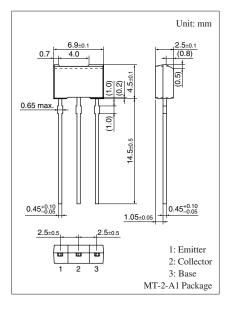
For DC-DC converter

■ Features

- ullet Low collector-emitter saturation voltage $V_{\text{CE(sat)}}$
- Low ON resistance Ron
- \bullet High forward current transfer ratio h_{FE}
- Allowing supply with radial taping

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V _{CBO}	25	V	
Collector-emitter voltage (Base open)	V _{CEO}	20	V	
Emitter-base voltage (Collector open)	V_{EBO}	12	V	
Collector current	I_C	0.5	A	
Peak collector current	I_{CP}	1	A	
Collector power dissipation *	P _C	1	W	
Junction temperature	T_{j}	150	°C	
Storage temperature	T _{stg}	-55 to +150	°C	



Note) *: Printed circuit board: Copper foil area of 1 cm² or more, and the board thickness of 1.7 mm for the collector portion

■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

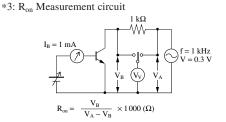
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V _{CBO}	$I_C = 10 \ \mu A, \ I_E = 0$	25			V
Collector-emitter voltage (Base open)	V _{CEO}	$I_C = 1 \text{ mA}, I_B = 0$	20			V
Emitter-base voltage (Collector open)	V _{EBO}	$I_E = 10 \ \mu A, I_C = 0$	12			V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = 25 \text{ V}, I_{E} = 0$			0.1	μΑ
Forward current transfer ratio *1	h _{FE1} *2	$V_{CE} = 2 \text{ V}, I_{C} = 500 \text{ mA}$	200		800	_
	h _{FE2}	$V_{CE} = 2 \text{ V}, I_{C} = 1 \text{ A}$	60			
Collector-emitter saturation voltage	V _{CE(sat)}	$I_C = 500 \text{ mA}, I_B = 20 \text{ mA}$		0.13	0.40	V
Base-emitter saturation voltage	V _{BE(sat)}	$I_C = 500 \text{ mA}, I_B = 50 \text{ mA}$			1.2	V
Transition frequency	f_T	$V_{CB} = 10 \text{ V}, I_E = -50 \text{ mA}, f = 200 \text{ MHz}$		200		MHz
Collector output capacitance	C _{ob}	$V_{CB} = 10 \text{ V}, I_{E} = 0, f = 1 \text{ MHz}$		10		pF
(Common base, input open circuited)						
ON resistanse *3	R _{on}			1.0		Ω

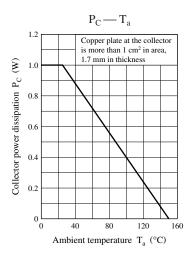
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

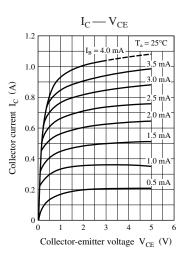
2. *1: Pulse measurement

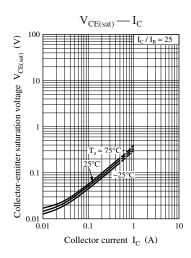
*2: Rank classification

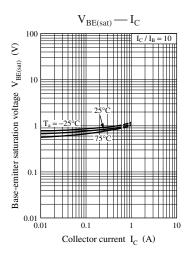
Rank	R	S	Т
$h_{\rm FE1}$	200 to 350	300 to 500	400 to 800

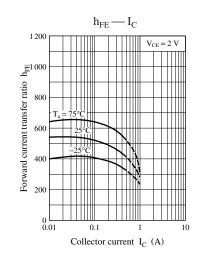


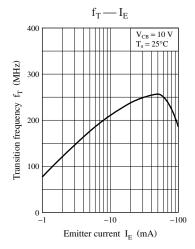


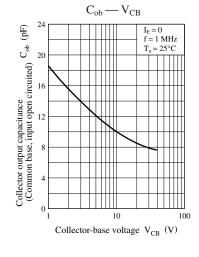


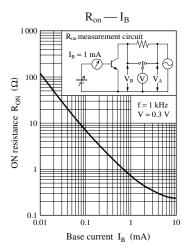












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